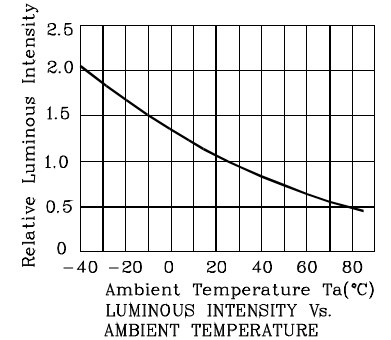
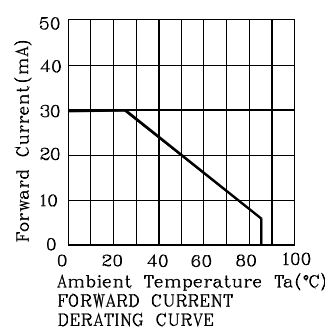
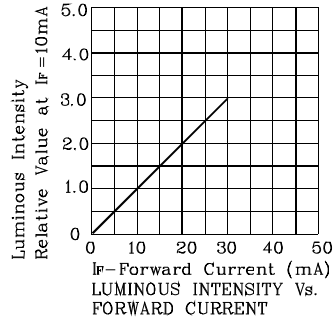
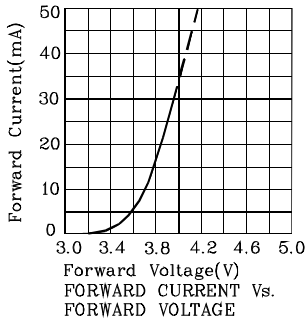
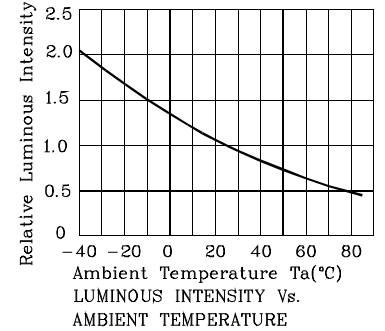
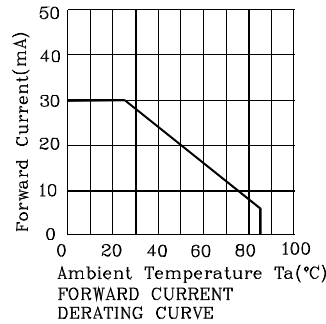
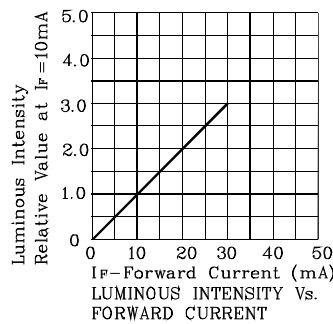
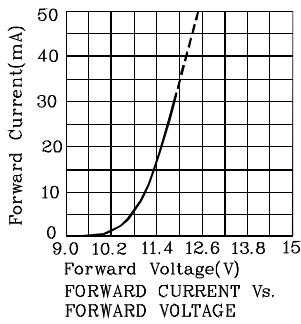
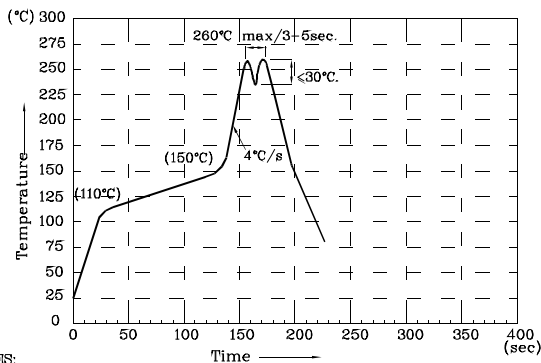


❖ MDK

RELATIVE INTENSITY Vs. WAVELENGTH



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- NOTES:
1. Recommend the wave temperature 245 $^\circ\text{C}$ ~260 $^\circ\text{C}$. The maximum soldering temperature should be less than 260 $^\circ\text{C}$.
 2. Do not apply stress on epoxy resins when temperature is over 85 $^\circ\text{C}$.
 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
 4. During wave soldering, the PCB top-surface temperature should be kept below 105 $^\circ\text{C}$.
 5. No more than once.

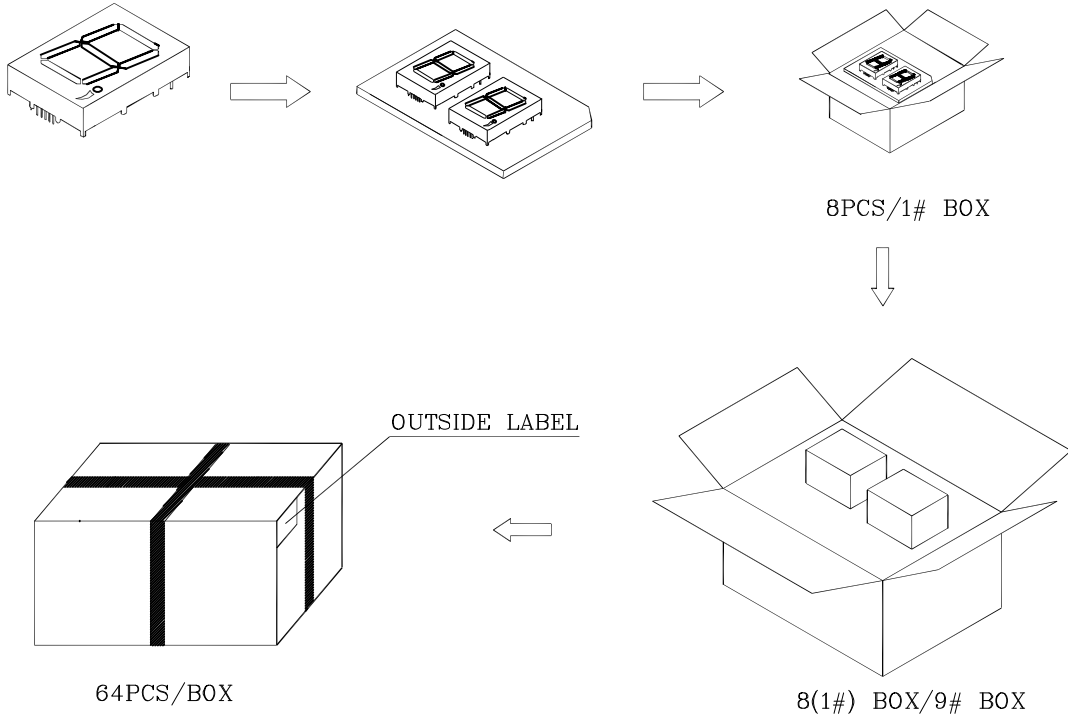
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

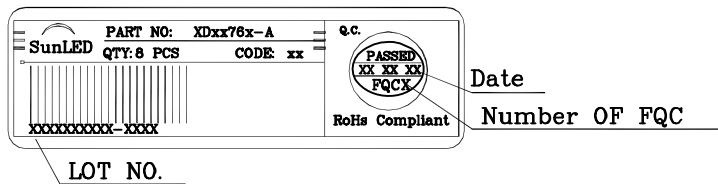
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



Inside Label On 1#BOX



Outside Label On Box

